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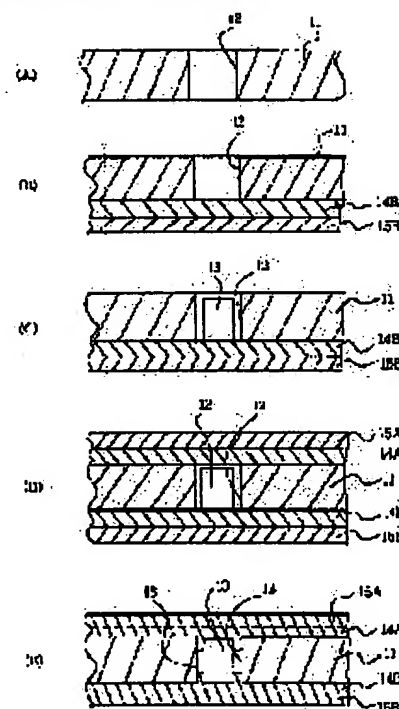
(72)Inventor : CHOKAI MAKOTO
TANAKA HIROKAZU
YOSHIDA HIDEAKI

(54) THROUGH HOLE STRUCTURE FOR CERAMIC BOARD AND PRODUCTION THEREOF

(57)Abstract:

PURPOSE: To obtain a convenient structure of high power ceramic board in which conduction through a low resistance metal pin is allowed within a through hole made through the board.

CONSTITUTION: A metal pin 13 is loaded into a through hole 12 of a ceramic board 11 thus establishing electrical connection between conductor layers 15A, 15B on the surface and the rear. More specifically, Aluminium plates 15A, 15B are secured through aluminium based brazing materials 14A, 14B to the surface and the rear of the AlN board 11, respectively. The pin 13 made of an aluminium alloy is previously inserted into the through hole 12. Subsequently, the brazing materials 14A, 14B are fused and jointed to the pin 13 thus filling the through hole 12 with the pin 13 and ensuring conduction between the aluminium plates 15A, 15B on the surface and the rear.



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